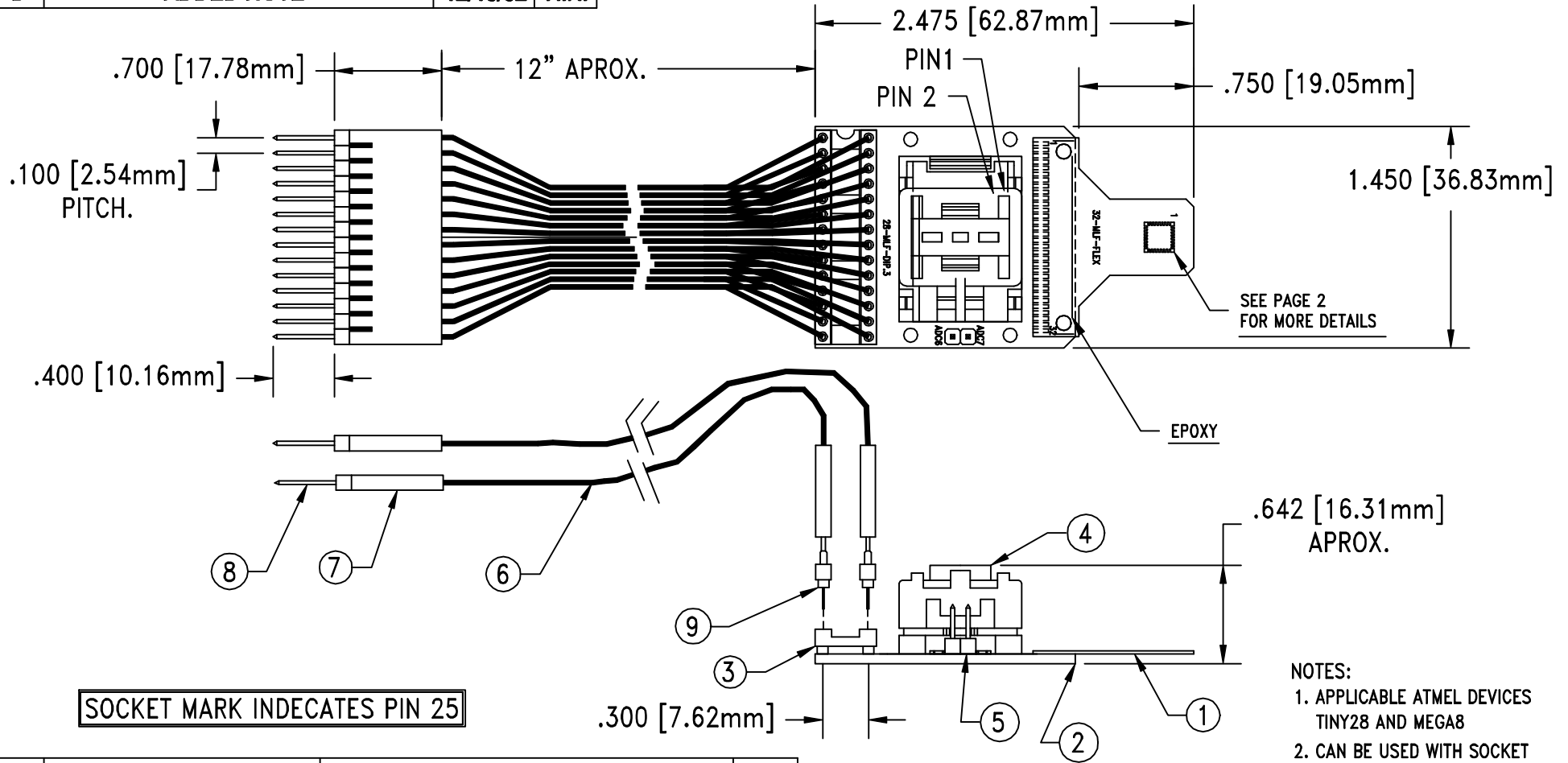



| REV | DESCRIPTION | DATE | INIT |
|-----|-------------|----------|------|
| A | NEW DRAWING | 10-24-02 | M.D. |
| B | ADDED NOTE | 12/16/02 | H.N. |

F6730
DOD 36730



| NO. | ITEM | DESCRIPTION | QTY. |
|-----|----------------|---------------------------|-------|
| 1 | 32-MLF-FLEX | FLEXIBLE SIDE BOARD | 1 |
| 2 | 28-MLF-DIP.3 | RIGID SIDE BOARD | 1 |
| 3 | S-DIP-00-028-C | SOLDER TO TOP #2 | 1 |
| 4 | S-MLF-00-032-A | SOLDER TO TOP #2 | 1 |
| 5 | WWPOST-36-AS | SOLDDET TO TOP #2 | .1 |
| 6 | CABLE | 2 PCS OF 12 INCHES | 24 IN |
| 7 | CON-C-20-1-F | CUT TO 14 PIN USE WITH #6 | 4 |
| 8 | WWPOST-36-PGA | PLUG INTO 1 SIDE #7 | 1 |
| 9 | WWPOST-36-AS-M | SHIP WITH KIT | 1 |

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



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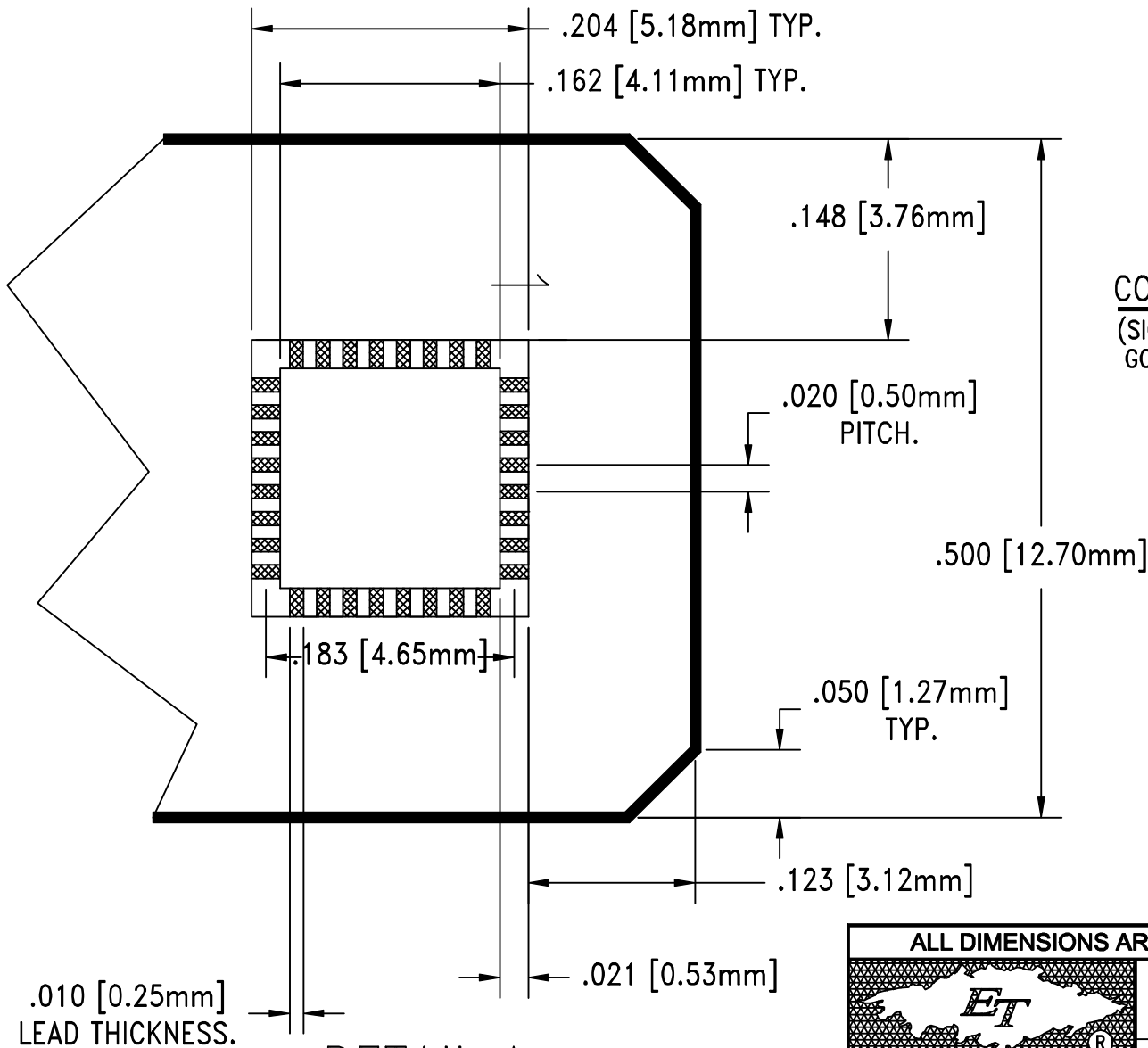
2344 Walsh Ave, Bldg. F Santa Clara, CA 95051
TEL: (408) 982-0660
FAX: (408) 982-0664

| | | | |
|-----------------------|--------------------------|--------------------|---------------------------------------|
| SHEET: 1 OF 2 | DATE: 06/14/02 | REVISION: B | ASSEMBLY DRAWING |
| CHECKED: PERRY MONROE | DRAWN: MIGUEL DELGADILLO | ITEM: BC-X-040/S-3 | DESCRIPTION: BCP-032-ML04Z-MEGA8-3IN1 |

DO NOT SCALE DRAWING

| REV | DESCRIPTION | DATE | INIT |
|-----|-------------|----------|------|
| A | NEW DRAWING | 10-24-02 | M.D. |

F6730
DOD 36730



CONNECTION TABLE
(SIGNALS ADC6 and ADC7
GO TO PIN HEADERS)

| QFP/MLF | DIP | COMMENTS |
|---------|-----|----------|
| 1 | 5 | PD3 |
| 2 | 6 | PD4 |
| 3 | | GND |
| 4 | 7 | VCC |
| 5 | 8 | GND |
| 6 | | VCC |
| 7 | 9 | PB6 |
| 8 | 10 | PB7 |
| 9 | 11 | PD5 |
| 10 | 12 | PD6 |
| 11 | 13 | PD7 |
| 12 | 14 | PB0 |
| 13 | 15 | PB1 |
| 14 | 16 | PB2 |
| 15 | 17 | PB3 |
| 16 | 18 | PB4 |
| 17 | 19 | PB5 |
| 18 | 20 | AVCC |
| 19 | | ADC6 |
| 20 | 21 | AREF |
| 21 | 22 | AGND |
| 22 | | ADC7 |
| 23 | 23 | PC0 |
| 24 | 24 | PC1 |
| 25 | 25 | PC2 |
| 26 | 26 | PC3 |
| 27 | 27 | PC4 |
| 28 | 28 | PC5 |
| 29 | 1 | PC6 |
| 30 | 2 | PD0 |
| 31 | 3 | PD1 |
| 32 | 4 | PD2 |

DETAIL A

SCALE 8:1

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



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SHEET:
2 OF 2

DATE:
10-24-02

REVISION:

ASSEMBLY DRAWING

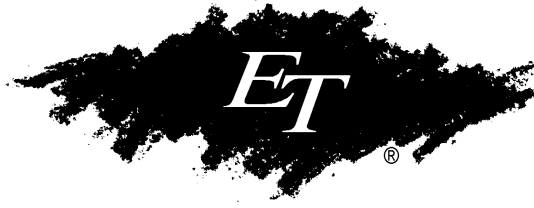
CHECKED:
PERRY MONROE

DRAWN:
MIGUEL DELGADILLO

ITEM:
BC-X-040/S-3

DO NOT SCALE DRAWING

DESCRIPTION:
BCP-032-ML04Z-MEGA8-3IN1



EMULATION TECHNOLOGY, INC.

MLF Flex Adapter User Instructions

Emulation Technology's new MLF Flex Interface Probe quickens the debug process and your time to market. This probe is multipurpose and provides signal access and instrument access to your target board. MLF Flex Interface Probe allows you to quickly and easily configure and interface to an in-circuit emulator, device programmer, logic analyzer or oscilloscope. You can change and test different chip packages, monitor performance and program MLF devices with ease and without the need of soldering MLF chip packages to your target board.

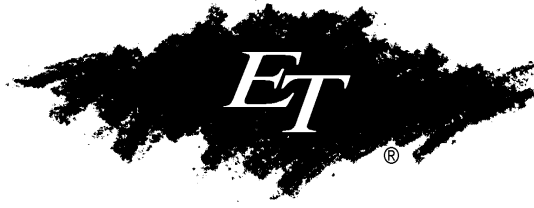
SUGGESTED SUPPLIES

63/37 or 60/40 Solder Paste
Flux paste, 10cc No-clean (ET Part# CQ291E)
Flux Remover, Chemtronics, Flux Off 2000
Tape (Masking, Scotch, etc.)

SUGGESTED EQUIPMENT

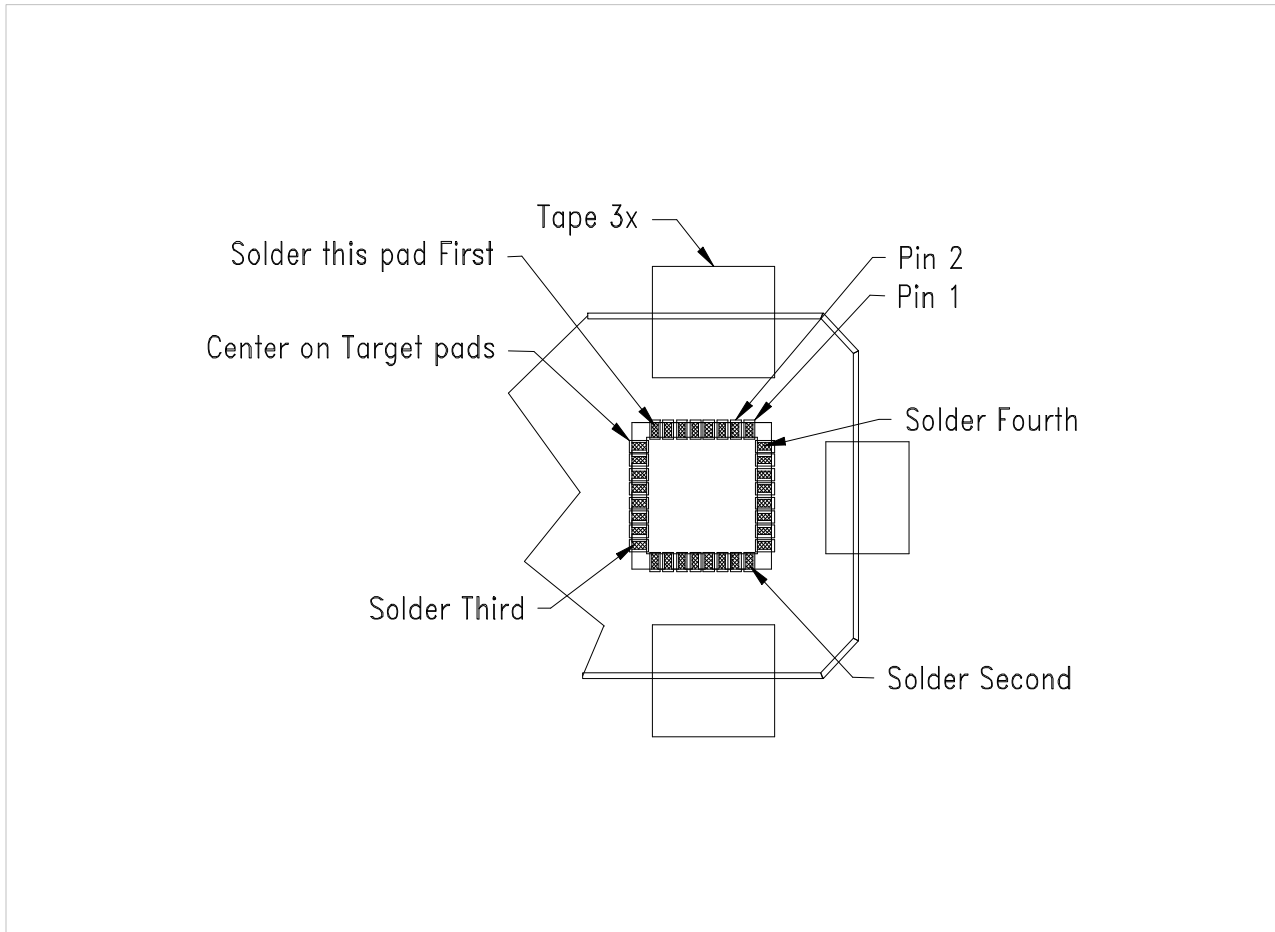
Microscope
Soldering Iron
Fine Tip for Soldering Iron

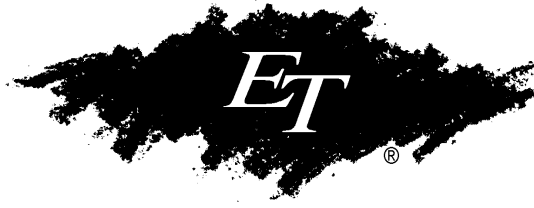
1. Under microscope, pre-tin solder pads of MLF Footprint to create consistent solder "bumps".
2. Apply liquid flux as required to the target footprint.
3. Apply 3 pieces of tape (1/4" x 1/4" sq.) to the sides of Flex Interface Probe (See Detail A for tape placement).
4. Slide Flex Interface Probe over the target footprint and align up the center of target board pads. Press down on the tape to hold in place.
5. Begin solder reflow of Flex Interface Probe to the target board pad pattern by touching the solder tip to the four corners first to secure the adapter in correct alignment, then finish the rest of pads. (See Detail A&B).
6. Clean solder joints with Flux remover.
7. Carefully configure Flex Interface Probe for emulation, programming or logic analysis.



EMULATION TECHNOLOGY, INC.

DETAIL A





EMULATION TECHNOLOGY, INC.

DETAIL B

